

SOMATAC® TE

APPLICATIONS

- For electronic component processing
- For wafer polishing

SOMATAC® TE Series are thermal expansion (foaming) adhesive films, which can be peeled off by heating.

Various types of SOMATAC® TE Series products with different thermal foaming temperatures and releasing strengths are available.

Features

- Before foaming, the product displays strong peeling strength which improves operating efficiency.
- After heating, it can be peeled off easily leaving no adhesive residue.
- As the foaming layer is thin, thermal conduction speed is fast and processing time could be shortened.
- Double-sided lamination is possible (non-base-material type).

